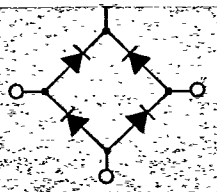
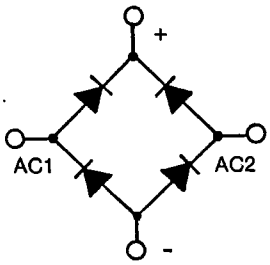
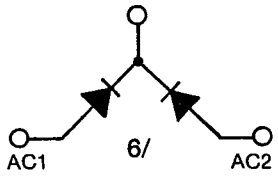
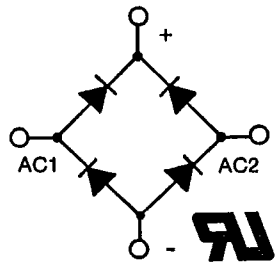
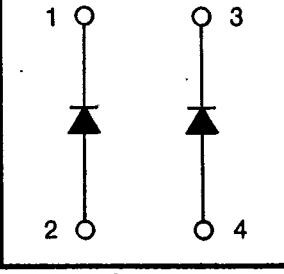


DIP Silicon Rec

RATINGS & CHARACTERISTICS 6

CIRCUIT	Schmatic Diagram	Type No.	Mazimum Working Peak Reverse Voltage VRM (wkg) & VR 1/ Volts	Maximum RMS Input Voltage 2/ 4/ Volts	Maximum Transient Rated Voltage 1/ Volts	Maximum Average Output Current @ TA=40°C 3/ 4/ Amps	Maximum RMS Output Current @ TA=40°C 3/ 4/ Amps	Maximum Repetitive Peak Output Current @ TA=40°C 5/ Amps
STANDARD BRIDGE		CSB05	50	35	70	1.0	1.11	10
		CSB1	100	70	150	1.0	1.11	10
		CSB2	200	140	240	1.0	1.11	10
		CSB4	400	280	480	1.0	1.11	10
		CSB6	600	420	700	1.0	1.11	10
		CSB8	800	560	900	1.0	1.11	10
		CSB10	1000	700	1100	1.0	1.11	10
HIGH VOLT-AGE BRIDGE		CKB8	800	560	1000	0.5	0.55	5
		CKB10	1000	700	1200	0.5	0.55	5
		CKB12	1200	840	1400	0.5	0.55	5
CENTER TAP		PKC05	50	35	70	1.60	1.78	10
		PKC1	100	70	150	1.60	1.78	10
		PKC2	200	140	240	1.60	1.78	10
		PKC4	400	280	480	1.60	1.78	10
		PKC6	600	420	700	1.60	1.78	10
		PKC8	800	560	1000	0.75	0.83	5
		PKC10	1000	700	1200	0.75	0.83	5
		PKC12	1200	840	1400	0.75	0.83	5
FAST SWITCHING BRIDGE		CSB05F	50	35	70	.8	.9	8
		CSB1F	100	70	150	.8	.9	8
		CSB2F	200	140	240	.8	.9	8
		CSB4F	400	280	480	.8	.9	8
		CSB6F	600	420	700	.8	.9	8
		CSB8F	800	560	900	.8	.9	8
ISOLATED DUAL DIODES		PKI05	50	35	70	0.80	1.26	10
		PKI1	100	70	150	0.80	1.26	10
		PKI2	200	140	240	0.80	1.26	10
		PKI4	400	280	480	0.80	1.26	10
		PKI6	600	420	700	0.80	1.26	10
		PKI8	800	560	1000	0.38	0.60	5
		PKI10	1000	700	1200	0.38	0.60	5
		PKI12	1200	840	1400	0.38	0.60	5

NOTES:

1/ Per rectifier element

2/ For center-tap configurations input voltages shown are line to line

3/ For doubler configurations currents and voltages as specified are output contribution when device is being utilized as part of a single or three phase bridge

4/ For isolated diode configuration are per diode element

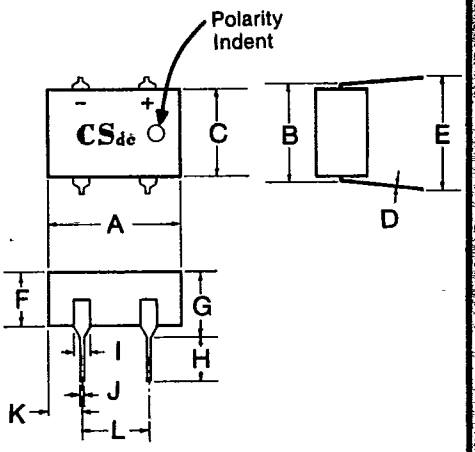
5/ For 1.0 milli-second duration per

6/ Negative output center tap confi changing 'P' in part number to 'N'

ifiers by CSdc

hertz, inductive/resistive load:

Maximum Reverse Recovery Time trr @ TA = 25°C 1/ 8/ Nano-Sec	Typical Junction to Ambient Thermal Resistance Θja °C/Watt	Maximum Single Cycle Surge Current 1/ Amps	Maximum Peak Forward Voltage VFM @ TA=25° C & IFM=1.0Apk 1/ Volts	Maximum D.C. Reverse Current IR@ VR & 1/ TA= 25° C uAmps	Maximum D.C. Reverse Current IR@ VR & 1/ TA= 135°C uAmps	Terminal Identification (top view)	Outline Dimensions (For all circuit configurations)
—	35	30	1.2	5.0	100		
—	35	30	1.2	5.0	100		
—	35	30	1.2	5.0	100		
—	35	30	1.2	5.0	100		
—	35	30	1.2	5.0	100		
—	35	30	1.2	5.0	100		
—	35	30	1.2	5.0	100	+ AC1 - AC2	
—	67	25	2.4	5.0	100		
—	67	25	2.4	5.0	100		
—	67	25	2.4	5.0	100		
—	40	30	1.2	5.0	100		
—	40	30	1.2	5.0	100		
—	40	30	1.2	5.0	100		
—	40	30	1.2	5.0	100		
—	40	30	1.2	5.0	100		
—	85	25	2.4	5.0	100		
—	85	25	2.4	5.0	100		
—	85	25	2.4	5.0	100	+ AC1 7/ AC2	
200	40	25	1.4	5.0	100		
200	40	25	1.4	5.0	100		
200	40	25	1.4	5.0	100		
200	40	25	1.4	5.0	100		
250	40	25	1.4	5.0	100		
250	40	25	1.4	5.0	100	+ AC1 - AC2	
—	80	30	1.2	5.0	100		
—	80	30	1.2	5.0	100		
—	80	30	1.2	5.0	100		
—	80	30	1.2	5.0	100		
—	80	30	1.2	5.0	100		
—	170	25	2.4	5.0	100		
—	170	25	2.4	5.0	100		
—	170	25	2.4	5.0	100	1 2 3 4	



Dimension	Inches	Millimeters
A	.370-.390	9.40-9.91
B	.280-.320	7.11-8.13
C	.240-.260	6.10-6.60
D	.008-.015	0.20-0.38
E	.300-.340	8.64 Max
F	.140-.160	3.56-4.06
G	.217 Max	5.51 Max
H	.120-.130	3.05-3.30
I	.040-.060	1.02-1.52
J	.016-.020	0.41-0.51
K	.080-.100	2.03-2.54
L	.190-.210	4.83-5.33

utput currents as specified

nducting cycle

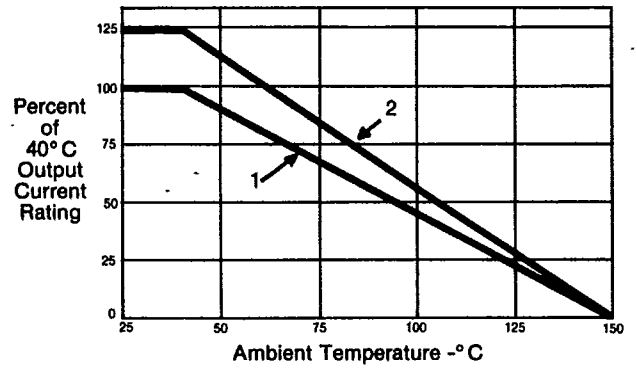
uration is also available by

7/ For negative output center tap configuration this terminal is negative output

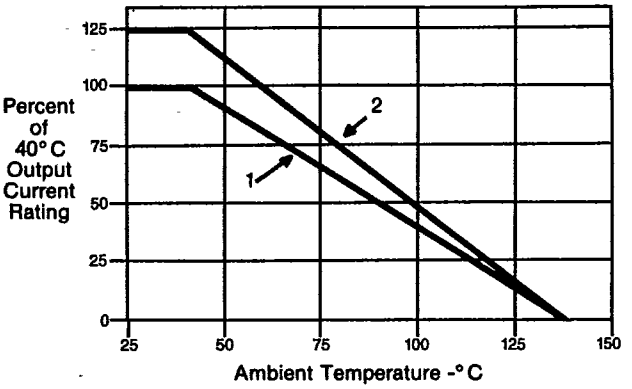
8/ Recovery test conditions are per (MIL-S-19500/286C): IFM = 0.5Apk; IRR = 1.0Apk; Recover to 0.25Apk

RATING CURVES

50/60 HZ Device
Output Current De-Rating Schedule



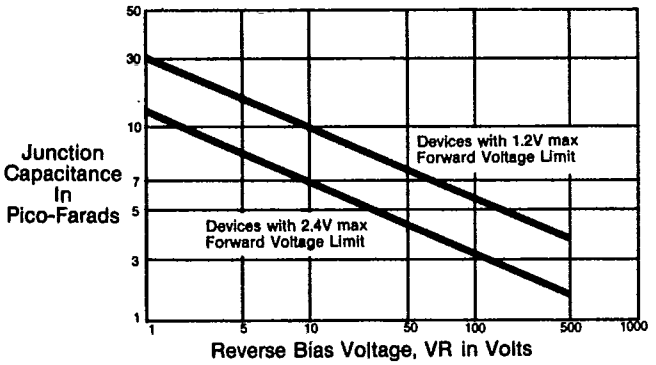
Fast Switching Device
Output Current De-Rating Schedule



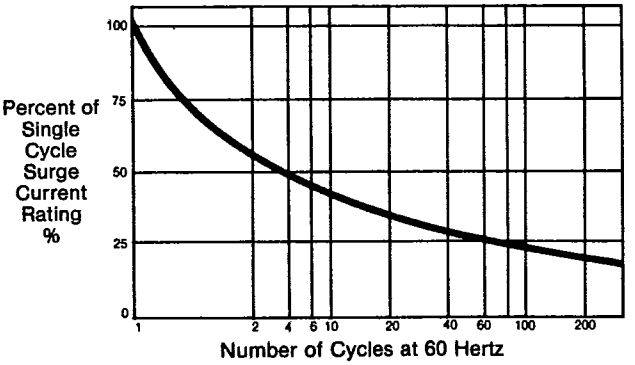
1. Minimum mounting heat sinking/similar as to when device is inserted into an IC DIP socket (with natural convection cooling.)

2. Device is inserted and soldered into a P-C board having individual terminal pad areas of 0.2 square inches minimum (with natural convectional cooling and with bottom/soldered side of the P-C board a minimum of 2 inches from adjacent surfaces).

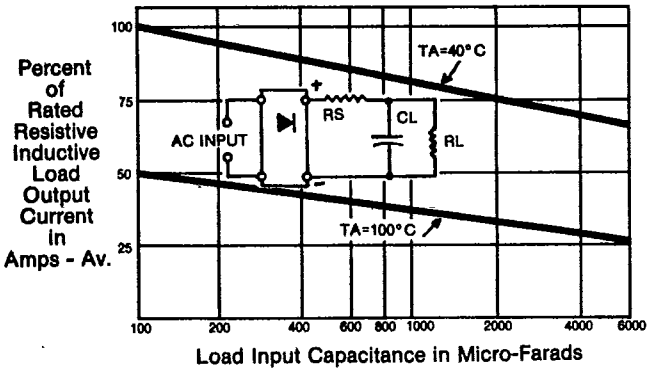
Typical Junction Capacitance Versus
Reverse Bias Voltage



Forward Surge Current Schedule
(over entire operational temperature range)



Rectified Average Output Current
For Capacitance/Resistance Loads



SERIES RESISTOR, Rs SELECTION TABLE		
Device Working Voltage Rating VPK	Rs OHMS	Wattage Rating* WATTS
50	5	2
100	10	5
200	15	10
400	25	15
600	40	25
800	50	30
1000	65	40
1200	80	50

*Based on 500 milliampere average continuous duty output current

Operating/Storage Temp Range: -55°C to 150°C (std switch type)
-55°C to 135°C (fast switch type)